

ABSTRACT OF THE DISCLOSURE

APPARATUS AND METHOD FOR REGULATING SURFACE TEMPERATURE OF POLISHING PAD

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There is disclosed an apparatus which can maintain a surface temperature of a polishing pad at a desired target temperature. The apparatus for regulating a surface temperature of a polishing pad, includes: a pad contact member which is contactable with a surface of the polishing pad and which has a heating flow passage and a cooling flow
10 passage formed therein; a heating-liquid supply pipe coupled to the heating flow passage; a cooling-liquid supply pipe coupled to the cooling flow passage; a first flow control valve attached to the heating-liquid supply pipe; a second flow control valve attached to the cooling-liquid supply pipe; a pad-temperature measuring device configured to measure a surface temperature of the polishing pad; and a valve controller configured to
15 operate the first flow control valve and the second flow control valve based on the surface temperature of the polishing pad.

FIG. 1